Application Data Sheet
Application Information

Application type:: Regular

Subject matter:: Utility

CD-ROM or CD-R:: None

Number of CD disks:: None

Number of copies of CDs:: None

Sequence submission?::

Computer readable form (CRF)?:: No

Number of copies of CRF::

Title:: UNDER BUMP METALLIZATION

STRUCTURE OF A SEMICONDUCTOR WAFER

Attorney docket number:: Huan 3212 Em

Request for early publication?:: No

Request for non-publication?:: No

Suggested drawing figure:: 2

Total drawing sheets:: 2

Small entity?:: No

Applicant Information

Applicant authority type:: Inventor

Primary citizenship country:: Taiwan, R.O.C.

Status: Full capacity

Given name:: Min-Lung

Middle name::

Family name:: HUANG

Name suffix::

City of Residence:: Kaohsiung, Taiwan 807, R.O.C.

State or province of residence::

Country of residence:: Taiwan, R.O.C.

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City of mailing address:: Kaohsiung, Taiwan 807, R.O.C.

State or province of mailing

address::

Country of mailing address:: Taiwan, R.O.C.

Postal or zip code of mailing

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Correspondence Information

Correspondence customer number:: 23364

Phone number:: 703-683-0500

Fax number:: 703-683-1080

E-mail address:: mail@baconthomas.com

Representative Information

Representative customer number:: 23364

Domestic Priority Information

Application:: Continuity Type:: Parent Parent Filing

Application:: Date::

Foreign Priority Information

Country:: Application number:: Filing Priority Date:: claimed::

TAIWAN, R.O.C. 092117897 June 30, YES

2003

Assignee Information

Assignee name:: Advanced Semiconductor

Engineering, Inc.

Street of mailing address:: 26 Chin 3rd Rd., Nantze Export

Processing Zone

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address::

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